ON Semiconductor

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ON Semiconductor®

FQB7N60 / FQI7N60

N-Channel QFET® MOSFET

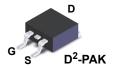
600 V, 7.4 A, 1.0 Ω

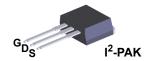
Description

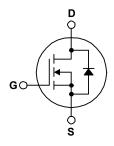
This N-Channel enhancement mode power MOSFET is produced using ON Semiconductor's proprietary planar stripe and DMOS technology. This advanced MOSFET technology has been especially tailored to reduce on-state resistance, and to provide superior switching performance and high avalanche energy strength. These devices are suitable for switched mode power supplies, active power factor correction (PFC), and electronic lamp ballasts.

Features

- 7.4 A, 600 V, $R_{DS(on)}$ = 1.0 Ω (Max.) @V_{GS} = 10 V, I_D = 3.7 A
- Low Gate Charge (Typ. 29 nC)
- Low Crss (Typ. 16 pF)
- 100% Avalanche Tested







Absolute Maximum Ratings T_C = 25°C unless otherwise noted.

Symbol	Parameter		FQB7N60TM FQB7N60TM-WS FQI7N60TU	Unit	
V _{DSS}	Drain-Source Voltage		600	V	
I _D	Drain Current - Continuous (T _C = 25°C)		7.4	Α	
	- Continuous (T _C = 100°C)		4.7	Α	
I _{DM}	Drain Current - Pulsed	(Note 1)	29.6	Α	
V _{GSS}	Gate-Source Voltage		± 30	V	
E _{AS}	Single Pulsed Avalanche Energy	(Note 2)	580	mJ	
I _{AR}	Avalanche Current	(Note 1)	7.4	Α	
E _{AR}	Repetitive Avalanche Energy	(Note 1)	14.2	mJ	
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	4.5	V/ns	
P_{D}	Power Dissipation (T _A = 25°C) *		3.13	W	
	Power Dissipation (T _C = 25°C)		142	W	
	- Derate above 25°C		1.14	W/°C	
T _J , T _{STG}	Operating and Storage Temperature Range		-55 to +150	°C	
T _L	Maximum Lead Temperature for Soldering, 1/8" from Case for 5 Seconds		300	°C	

Thermal Characteristics

Symbol	Parameter	FQB7N60TM FQB7N60TM-WS FQI7N60TU	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max. 0.88		
Ъ	Thermal Resistance, Junction to Ambient (Minimum Pad of 2-oz Copper), Max.	62.5	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (*1 in ² Pad of 2-oz Copper), Max.	40	

Package Marking and Ordering Information

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FQB7N60TM	FQB7N60	D ² -PAK	Tape and Reel	330 mm	24 mm	800 units
FQB7N60TM-WS	FQB7N60S	D ² -PAK	Tape and Reel	330 mm	24 mm	800 units
FQI7N60TU	FQI7N60	I ² -PAK	Tube	N/A	N/A	50 units

Electrical Characteristics T_C = 25°C unless otherwise noted.

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
Off Cha	aracteristics					
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	600			V
ΔBV _{DSS} / ΔT _J	Breakdown Voltage Temperature Coefficient	I _D = 250 μA, Referenced to 25°C		0.67		V/°C
I _{DSS}	Zana Cata Valtana Duain Comment	V _{DS} = 600 V, V _{GS} = 0 V			10	μΑ
	Zero Gate Voltage Drain Current	V _{DS} = 480 V, T _C = 125°C			100	μΑ
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = 30 V, V _{DS} = 0 V			100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	V _{GS} = -30 V, V _{DS} = 0 V			-100	nA
V _{GS(th)}	Gate Threshold Voltage Static Drain-Source	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$	3.0		5.0	V
R _{DS(on)}	Static Drain-Source					
()	On-Resistance	$V_{GS} = 10 \text{ V}, I_D = 3.7 \text{ A}$		8.0	1.0	Ω
g _{FS}	Forward Transconductance	$V_{DS} = 50 \text{ V}, I_{D} = 3.7 \text{ A}$		6.4		S
Dynam	ic Characteristics					
C _{iss}	Input Capacitance	V _{DS} = 25 V, V _{GS} = 0 V, f = 1.0 MHz		1100	1430	pF
C _{oss}	Output Capacitance			135	175	pF
C _{rss}	Reverse Transfer Capacitance			16	21	pF
Switchi	ing Characteristics		1	1	1	
t _{d(on)}	Turn-On Delay Time	V = 200 V I = 7.4 A		30	70	ns
,	1	$V_{DD} = 300 \text{ V} I_{D} = 7.4 \text{ A}$	1		1	

t _{d(on)}	Turn-On Delay Time	V _{DD} = 300 V, I _D = 7.4 A,	 30	70	ns
t _r	Turn-On Rise Time	$R_G = 25 \Omega$	 80	170	ns
t _{d(off)}	Turn-Off Delay Time		 65	140	ns
t _f	Turn-Off Fall Time	(Note 4)	 60	130	ns
Q_g	Total Gate Charge	V _{DS} = 480 V, I _D = 7.4 A,	 29	38	nC
Q _{gs}	Gate-Source Charge	V _{GS} = 10 V	 7		nC
Q _{gd}	Gate-Drain Charge	(Note 4)	 14.5		nC

Drain-Source Diode Characteristics and Maximum Ratings

I_S	Maximum Continuous Drain-Source Diode Forward Current		 	7.4	Α
I _{SM}	Maximum Pulsed Drain-Source Diode Forward Current		 	29.6	Α
V _{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0 V, I _S = 7.4 A	 	1.4	V
t _{rr}	Reverse Recovery Time	$V_{GS} = 0 \text{ V, } I_{S} = 7.4 \text{ A,}$	 320		ns
Q _{rr}	Reverse Recovery Charge	dI _F / dt = 100 A/μs	 2.4		μС

- Notes. 1. Repetitive rating : pulse-width limited by maximum junction temperature. 2. L = 19.5 mH, I_{AS} = 7.4 A, V_{DD} = 50 V, R_{G} = 25 Ω , starting T_{J} = 25°C. 3. I_{SD} ≤ 7.4 A, di/dt ≤ 200 A/ μ s, V_{DD} ≤ BV $_{DSS}$, starting T_{J} = 25°C. 4. Essentially independent of operating temperature.

Typical Characteristics

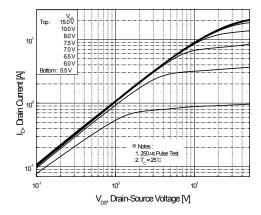


Figure 1. On-Region Characteristics

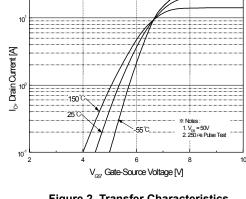


Figure 2. Transfer Characteristics

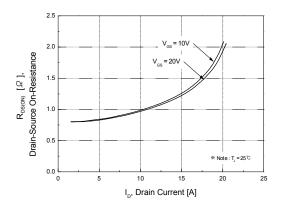


Figure 3. On-Resistance Variation vs. **Drain Current and Gate Voltage**

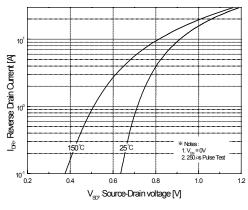


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

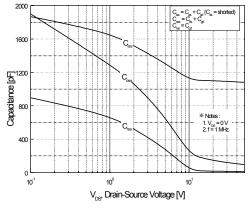


Figure 5. Capacitance Characteristics

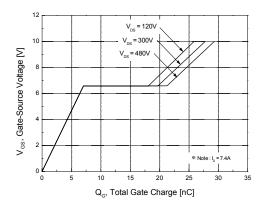


Figure 6. Gate Charge Characteristics

Typical Characteristics (Continued)

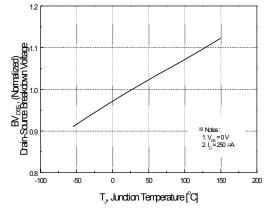


Figure 7. Breakdown Voltage Variation vs. Temperature

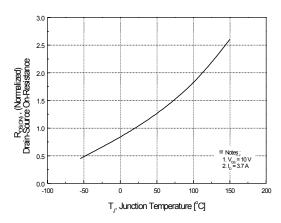


Figure 8. On-Resistance Variation vs. Temperature

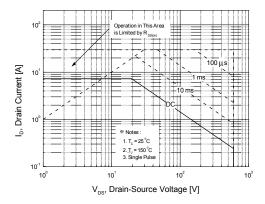


Figure 9. Maximum Safe Operating Area

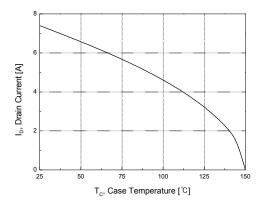


Figure 10. Maximum Drain Current vs. Case Temperature

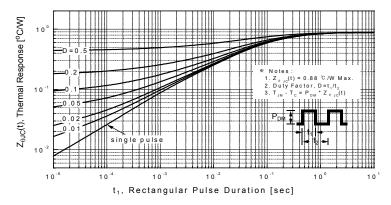


Figure 11. Transient Thermal Response Curve

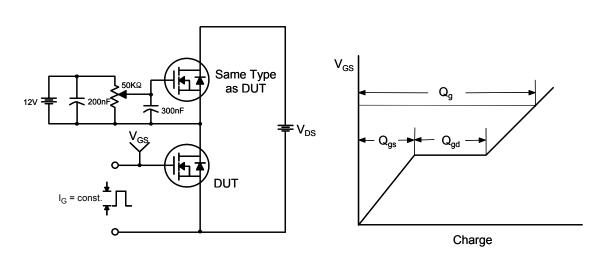


Figure 12. Gate Charge Test Circuit & Waveform

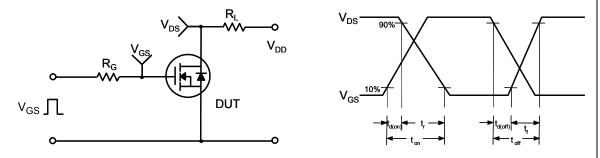


Figure 13. Resistive Switching Test Circuit & Waveforms

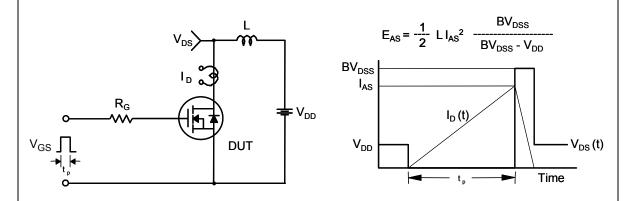
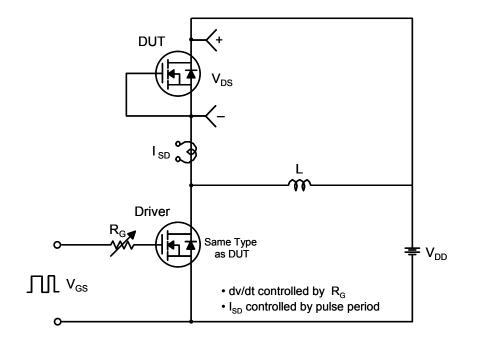


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms



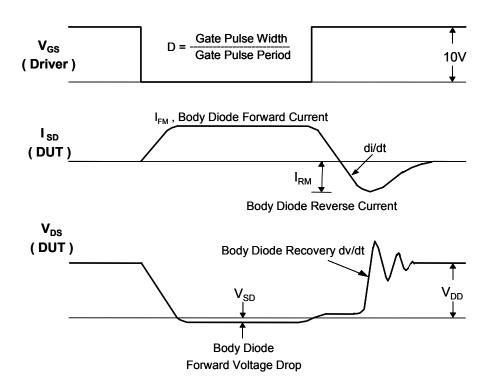


Figure 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms

Mechanical Dimensions

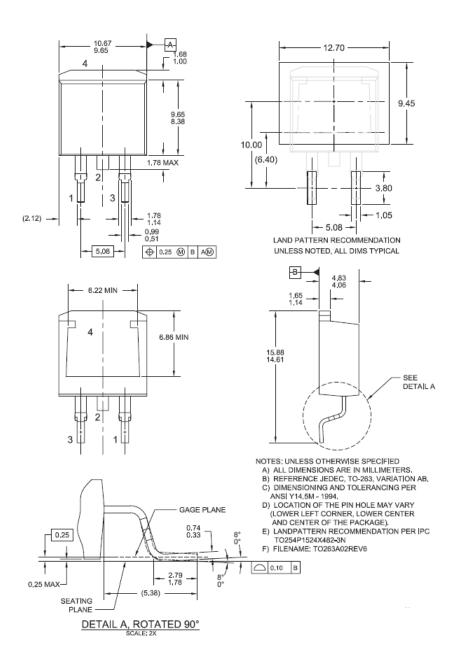
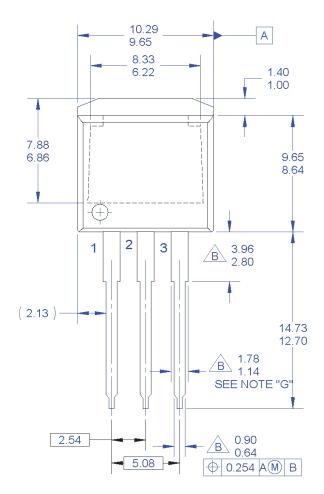
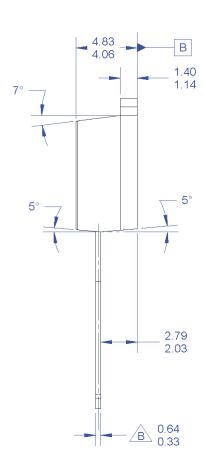


Figure 16. TO263 (D²PAK), Molded, 2-Lead, Surface Mount

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Mechanical Dimensions





NOTES:

A. EXCEPT WHERE NOTED CONFORMS TO
TO262 JEDEC VARIATION AA.

DOES NOT COMPLY JEDEC STD. VALUE.
C. ALL DIMENSIONS ARE IN MILLIMETERS.
D. DIMENSIONS ARE EXCLUSIVE OF BURRS.
MOLD FLASH AND TIE BAR PROTRUSIONS.
E. DIMENSION AND TOLERANCE AS PER ANSI
Y14.5-1994.
F. LOCATION OF PIN HOLE MAY VARY
(LOWER LEFT CORNER, LOWER CENTER
AND CENTER OF PACKAGE)
G. MAXIMUM WIDTH FOR F102 DEVICE = 1.35 MAX.
H. DRAWING FILE NAME: TO262A03REV5

Figure 17. TO262 (I²PAK), Molded, 3-Lead, Jedec Variation AA

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